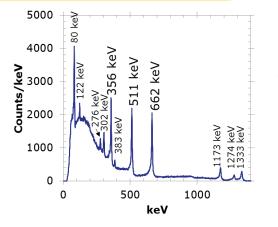


M400iC Integrable Imaging Spectrometer

Features

- ✓ Fast and highly portable spectrometer
- ✓ Gamma-ray imaging from 250 keV to 3 MeV
- Radiation image overlay onto optical image
- ✓ Option for ≤0.8% FWHM energy resolution at 662 keV and interaction-by-interaction resolution of ≤0.65% FWHM
- ✓ Ready to use in less than 90 s
- Rapidly identifies and localizes gamma-ray sources
- ✓ Industry-leading efficiency with up to >29 cm³ pixelated CZT
- Real-time spectroscopy and imaging
- ✓ Discrimination between background and sources of interest in less than 20 s
- Factory-configurable rugged DB9 connection for power and control
- ✓ Wireless, Ethernet, or USB communication
- ✓ Cleanable for decontamination
- Web-based user interface and full API for control and data readout



Integrate H3D's detector module into your product. This solution contains everything you need for highresolution spectroscopy and gamma-ray imaging.

Perfect for integration with:

- Drones
- Robots
- Other sensor suites

Containing the most advanced room-temperature semiconductor technology to achieve spectroscopic performance competitive with



cryogenically cooled detectors, the detector module has:

- Compact and light-weight size
- Fast startup
- Excellent energy resolution
- Integrated optical camera
- Low power
- Easy communication

Contact H3D to create a custom solution for your application.



The M400iC mounted on a drone.



The M400iC mounted on a drone

Extra-High-Efficiency Option (M400iC-15)

Increase crystal volume to >29 cm³. Also available as a higher-resolution M400iC+-15 with no resolution quarantee.

Lower-Efficiency Options

M200iC

Crystal Volume: >9.5 cm³ Sensitivity:

Detect in <44 s Locate in < 180 s

M100iC

Crystal Volume: >4.5 cm³ Sensitivity:

Detect in <88 s Locate in < 360 s

High-Resolution Option (M400iC⁺)

Improve energy resolution to ≤0.8% FWHM at 662 keV (coincident interactions combined) and ≤0.65% FWHM at 662 keV (coincident interactions separated)

Any options can be combined, except as noted.

Custom designs also available, including spectroscopy >3 MeV.





M400iC Base Specifications

Dimensions:

Weight: **Ingress Protection:**

Power Input:

Startup Time:

Energy Resolution at 25° C (77° F):

Sensitivity:

Spectroscopy Range: Image Energy Range: Optical Field of View: **Optical Registration:** Radiation Field of View: Angular Precision: Angular Resolution:

Crystal Volume: Count-Rate Limit: Maximum Event Rate:

Communication Options:

Data API Options:

4.5 in x 2.25 in x 5.0 in (11.4 cm x 5.7 cm x 12.7 cm) 2.2 lbs (1.0 kg) Designed to IP65

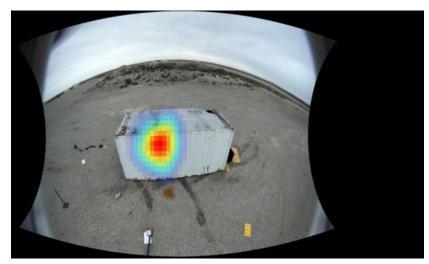
5 V, <9 W, through DB9 port Startup & Operating Temp.: -20° C to 50° C (-4° F to 122° F) with fan enabled -10° C to 35° C (14° F to 95° F) with fan disabled <90 s

> ≤1.1% FWHM at 662 keV (coincident interactions combined) ≤0.9% FWHM at 662 keV (coincident interactions separated) Detects 10- μ Ci ¹³⁷Cs at 1 m (~3 μ R/hr) in < 22 s (in natural background) Localize point source of 137 Cs producing \sim 3 µR/hr in <90 s

50 keV to 3 MeV 250 keV to 3 MeV >162° horizontal, >122° vertical; full color $\pm 2^{\circ}$ to radiation image in front $90^{\circ} \times 90^{\circ}$ 4п (360°) omnidirectional $\pm 1^{\circ}$ source localization for all 4π (real time) ~30° FWHM for all 4n (real time; >250 keV) \sim 20° FWHM for all 4 π (post processing; >250 keV)

>19 cm³ CZT (CdZnTe) 1 rem/hr (10 mSv/hr) bare-137Cs equivalent 150 kcps

USB to computer Ethernet Wireless communication interfaces available Real-time spectrum Event total energy, each interaction energy, and time stamp Each interaction 3D position (x, y, z)



A radiation source in a cargo container, imaged with the M400iC mounted on a drone.

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